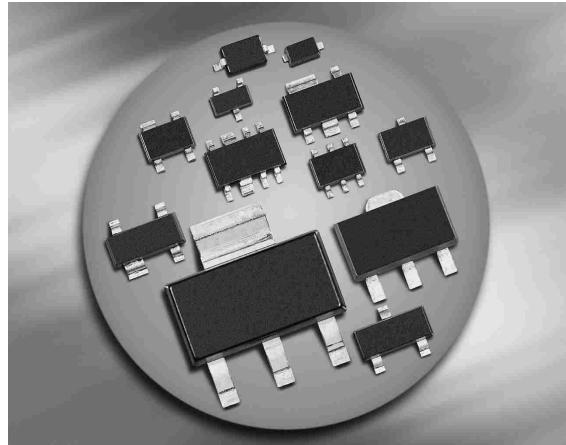
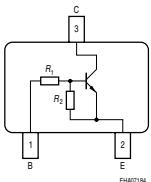
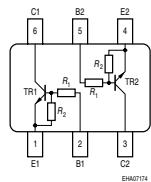


NPN Silicon Digital Transistor

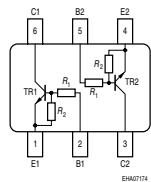
- Switching circuit, inverter, interface circuit driver circuit
- Built in bias resistor ($R_1=10\text{ k}\Omega$, $R_2=47\text{ k}\Omega$)
- BCR135S: Two internally isolated transistors with good matching in one multichip package



BCR135/F/L3
BCR135T/W



BCR135S



Type	Marking	Pin Configuration							Package
BCR135	WJs	1=B	2=E	3=C	-	-	-	-	SOT23
BCR135F	WJs	1=B	2=E	3=C	-	-	-	-	TSFP-3
BCR135L3	WJ	1=B	2=E	3=C	-	-	-	-	TSLP-3-4
BCR135S	WJs	1=E1	2=B1	3=C2	4=E2	5=B2	6=C1	-	SOT363
BCR135T	WJs	1=B	2=E	3=C	-	-	-	-	SC75
BCR135W	WJs	1=B	2=E	3=C	-	-	-	-	SOT323

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}	50	V
Collector-base voltage	V_{CBO}	50	
Emitter-base voltage	V_{EBO}	6	
Input on voltage	$V_{i(on)}$	20	
Collector current	I_C	100	mA
Total power dissipation BCR135, $T_S \leq 102^\circ\text{C}$ BCR135F, $T_S \leq 128^\circ\text{C}$ BCR135L3, $T_S \leq 135^\circ\text{C}$ BCR135S, $T_S \leq 115^\circ\text{C}$ BCR135T, $T_S \leq 109^\circ\text{C}$ BCR135W, $T_S \leq 124^\circ\text{C}$	P_{tot}	200 250 250 250 250 250	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾ BCR135 BCR135F BCR135L3 BCR135S BCR135T BCR135W	R_{thJS}	≤ 240 ≤ 90 ≤ 60 ≤ 140 ≤ 165 ≤ 105	K/W

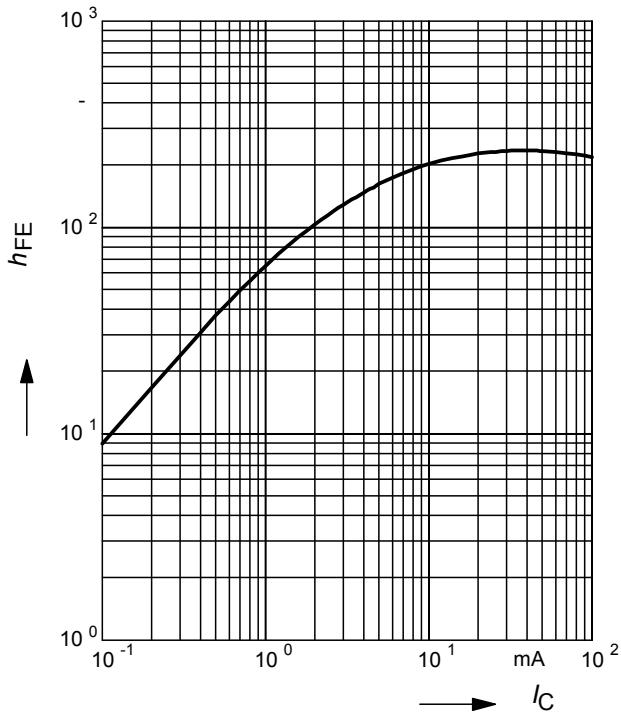
¹⁾For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

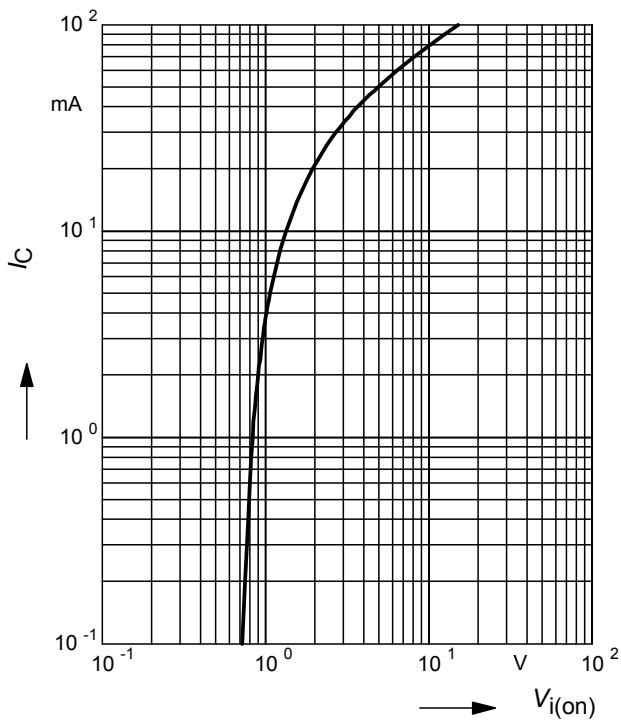
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage $I_C = 100 \mu\text{A}, I_B = 0$	$V_{(\text{BR})\text{CEO}}$	50	-	-	V
Collector-base breakdown voltage $I_C = 10 \mu\text{A}, I_E = 0$	$V_{(\text{BR})\text{CBO}}$	50	-	-	
Collector-base cutoff current $V_{CB} = 40 \text{ V}, I_E = 0$	I_{CBO}	-	-	100	nA
Emitter-base cutoff current $V_{EB} = 6 \text{ V}, I_C = 0$	I_{EBO}	-	-	167	μA
DC current gain ¹⁾ $I_C = 5 \text{ mA}, V_{CE} = 5 \text{ V}$	h_{FE}	70	-	-	-
Collector-emitter saturation voltage ¹⁾ $I_C = 10 \text{ mA}, I_B = 0.5 \text{ mA}$	V_{CEsat}	-	-	0.3	V
Input off voltage $I_C = 100 \mu\text{A}, V_{CE} = 5 \text{ V}$	$V_{i(\text{off})}$	0.5	-	1	
Input on voltage $I_C = 2 \text{ mA}, V_{CE} = 0.3 \text{ V}$	$V_{i(\text{on})}$	0.5	-	1.4	
Input resistor	R_1	7	10	13	k Ω
Resistor ratio	R_1/R_2	0.19	0.21	0.24	-
AC Characteristics					
Transition frequency $I_C = 10 \text{ mA}, V_{CE} = 5 \text{ V}, f = 100 \text{ MHz}$	f_T	-	150	-	MHz
Collector-base capacitance $V_{CB} = 10 \text{ V}, f = 1 \text{ MHz}$	C_{cb}	-	3	-	pF

¹Pulse test: $t < 300\mu\text{s}$; $D < 2\%$

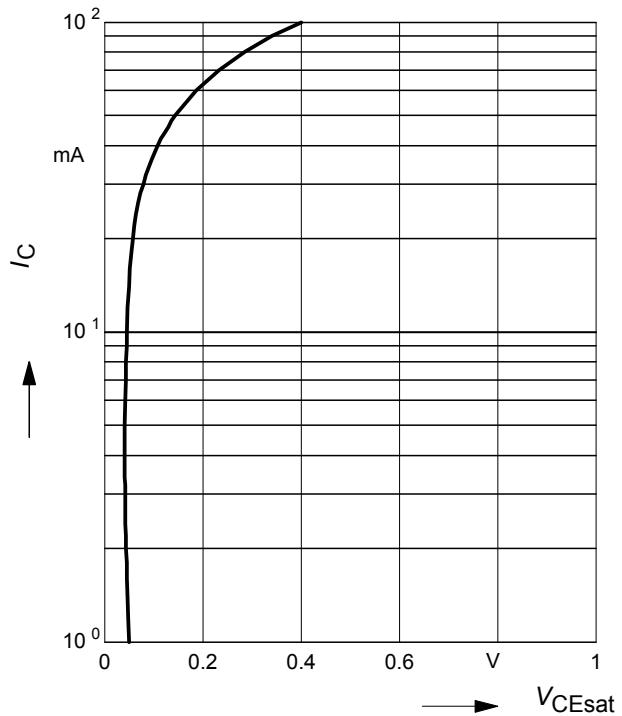
DC current gain $h_{FE} = f(I_C)$
 $V_{CE} = 5V$ (common emitter configuration)



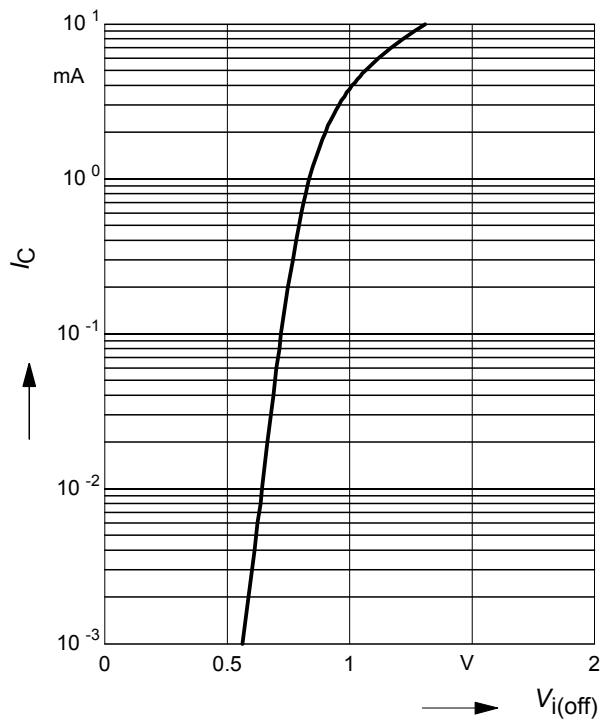
Input on Voltage $V_{i(on)} = f(I_C)$
 $V_{CE} = 0.3V$ (common emitter configuration)



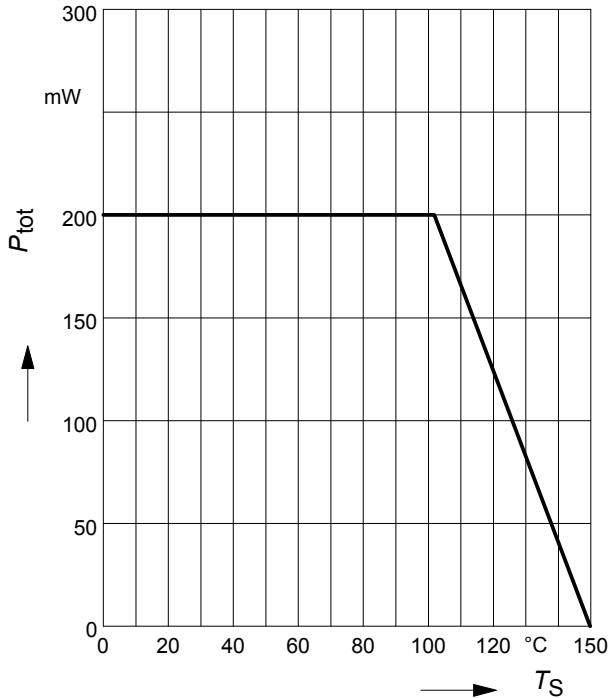
Collector-emitter saturation voltage
 $V_{CEsat} = f(I_C), h_{FE} = 20$



Input off voltage $V_{i(off)} = f(I_C)$
 $V_{CE} = 5V$ (common emitter configuration)

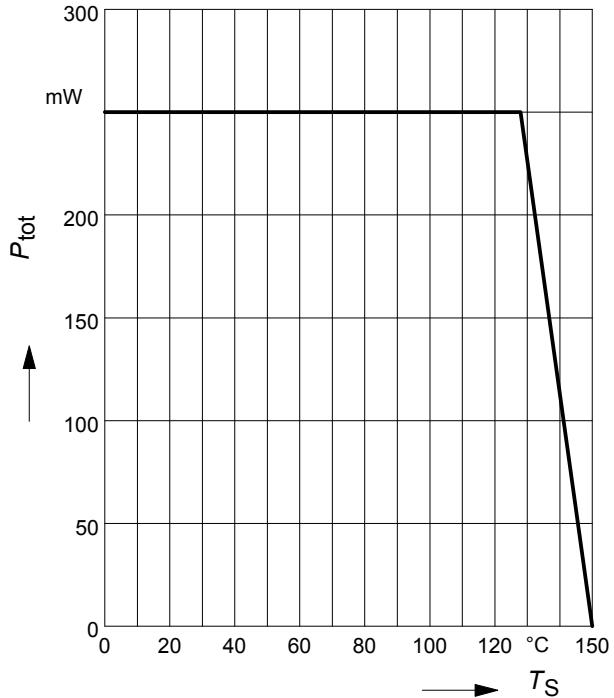


Total power dissipation $P_{\text{tot}} = f(T_S)$
BCR135



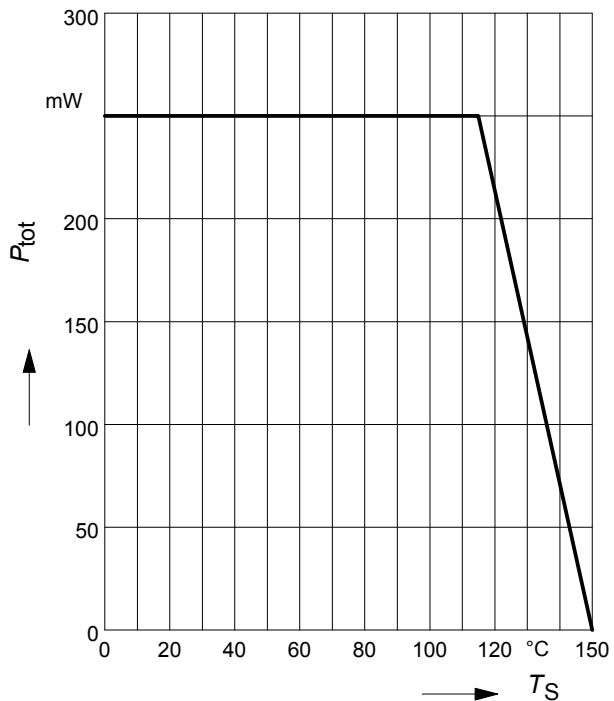
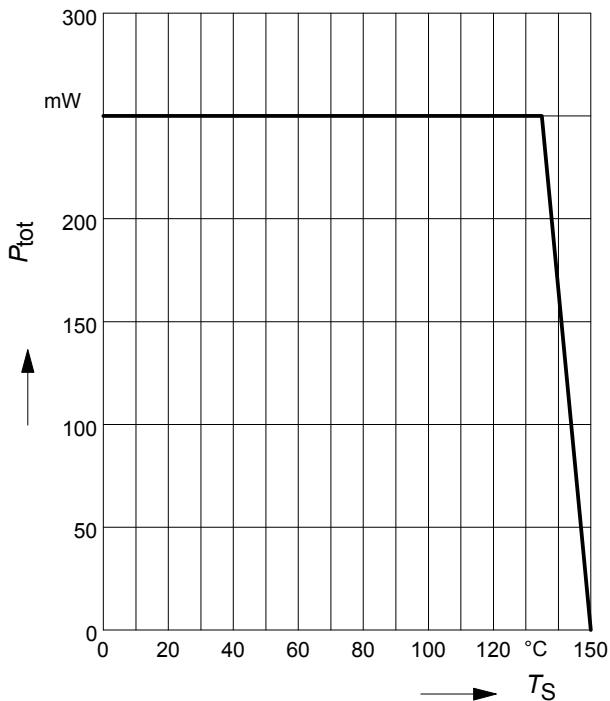
Total power dissipation $P_{\text{tot}} = f(T_S)$
BCR135F

Total power dissipation $P_{\text{tot}} = f(T_S)$
BCR135F

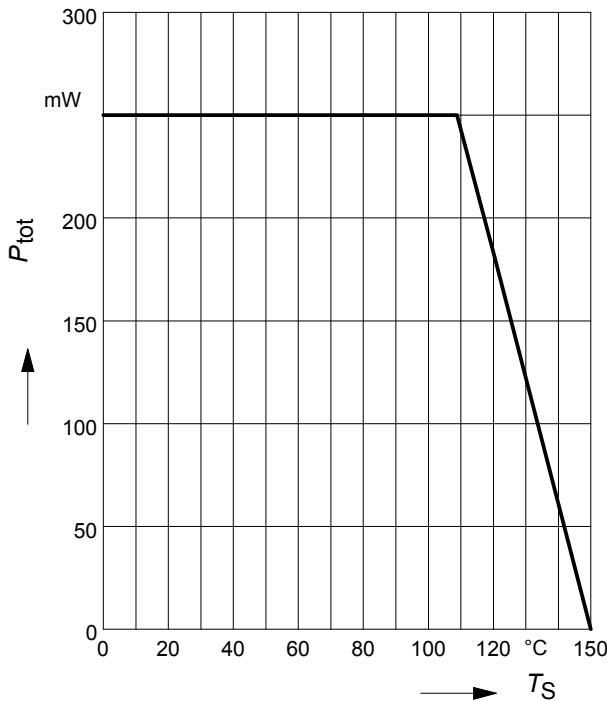


Total power dissipation $P_{\text{tot}} = f(T_S)$
BCR135L3

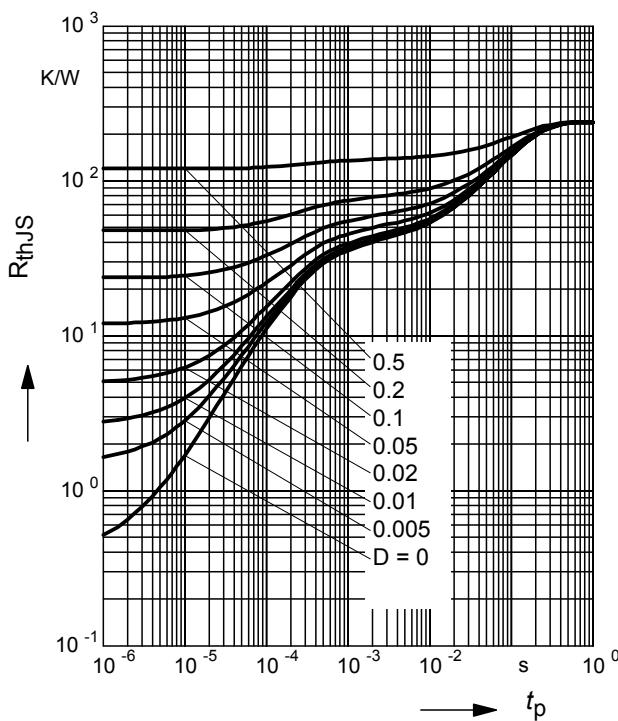
Total power dissipation $P_{\text{tot}} = f(T_S)$
BCR135S



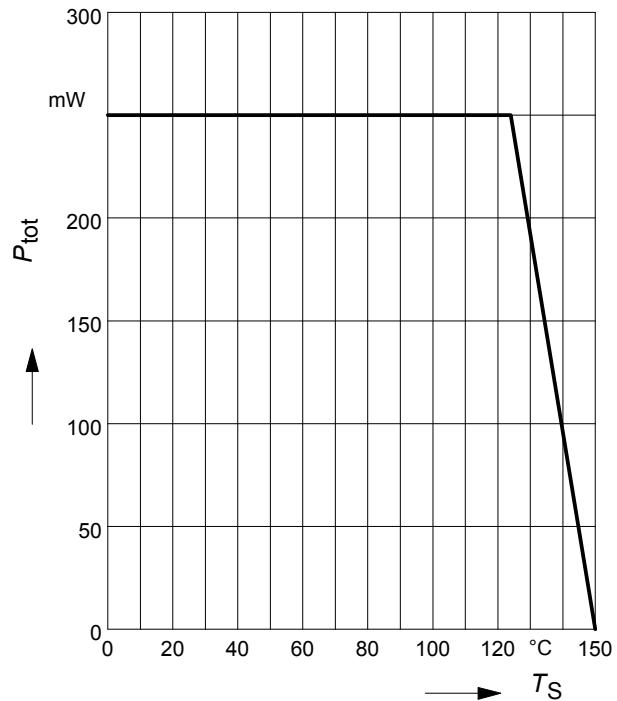
Total power dissipation $P_{\text{tot}} = f(T_S)$
BCR135T



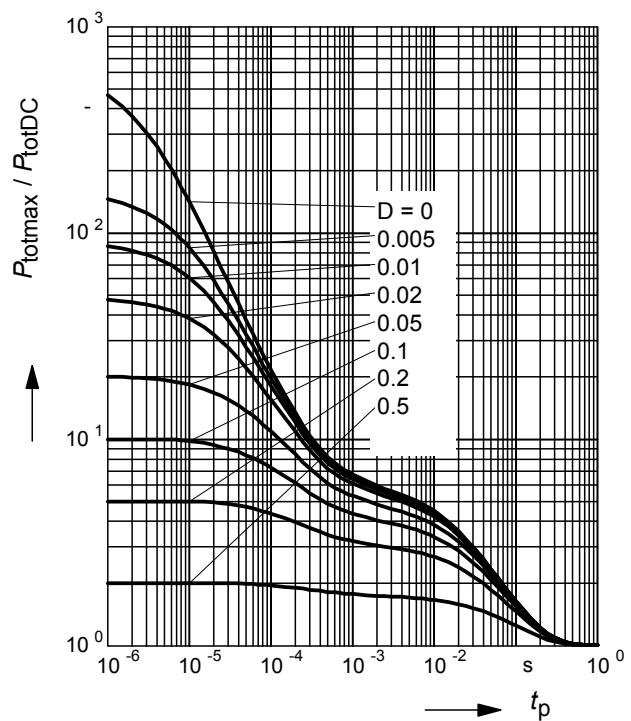
Permissible Pulse Load $R_{\text{thJS}} = f(t_p)$
BCR135



Total power dissipation $P_{\text{tot}} = f(T_S)$
BCR135W

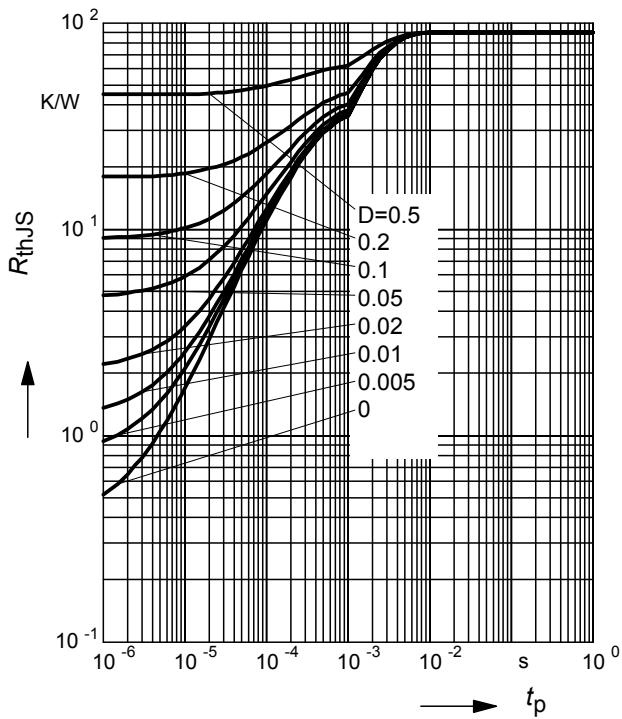


Permissible Pulse Load
 $P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$
BCR135

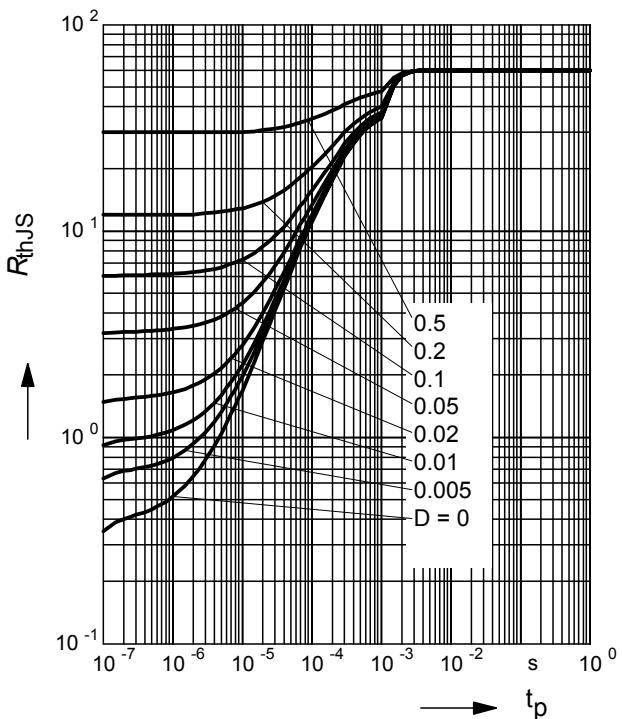


Permissible Puls Load $R_{\text{thJS}} = f(t_p)$

BCR135F

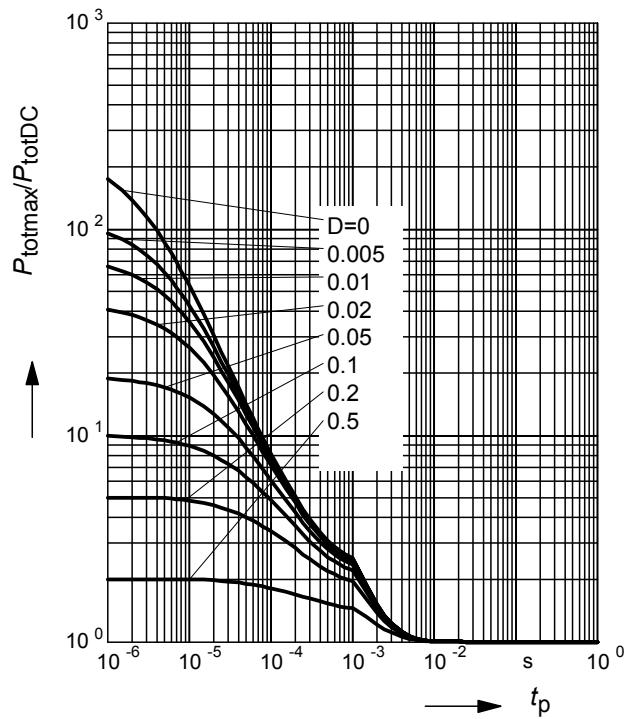

Permissible Puls Load $R_{\text{thJS}} = f(t_p)$

BCR135L3


Permissible Pulse Load

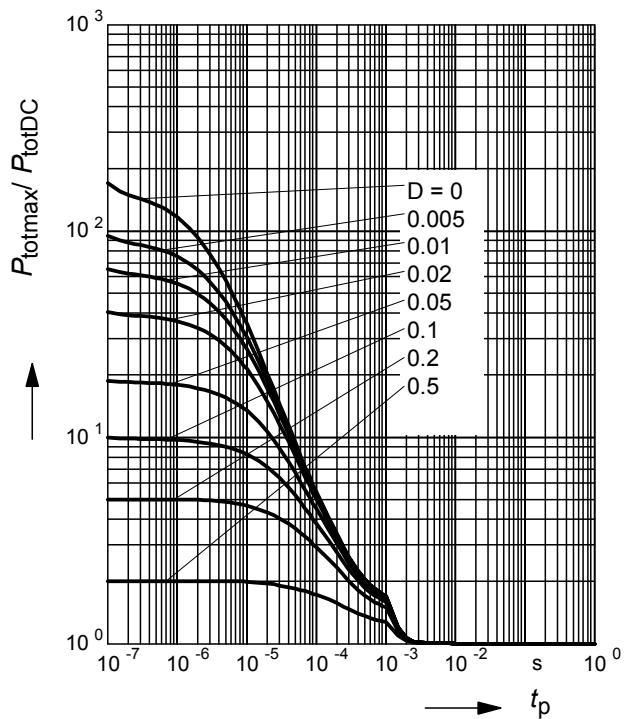
$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$$

BCR135F


Permissible Pulse Load

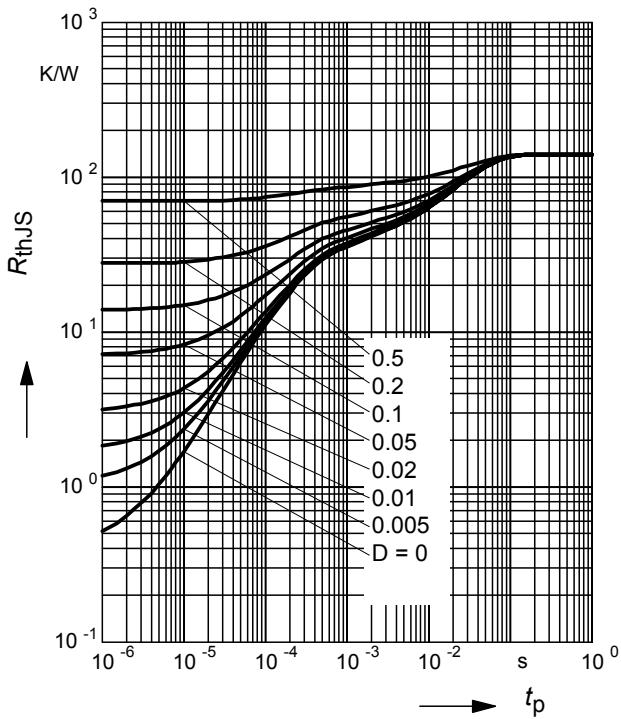
$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$$

BCR135L3

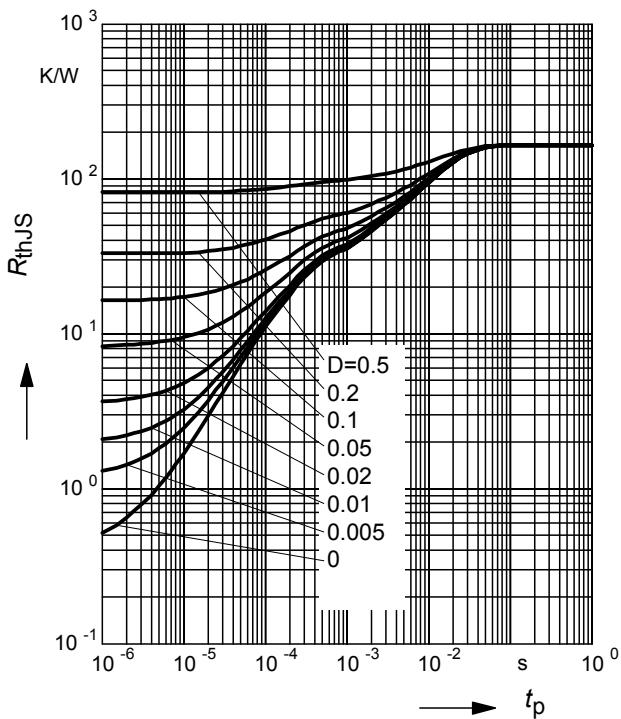


Permissible Puls Load $R_{\text{thJS}} = f(t_p)$

BCR135S

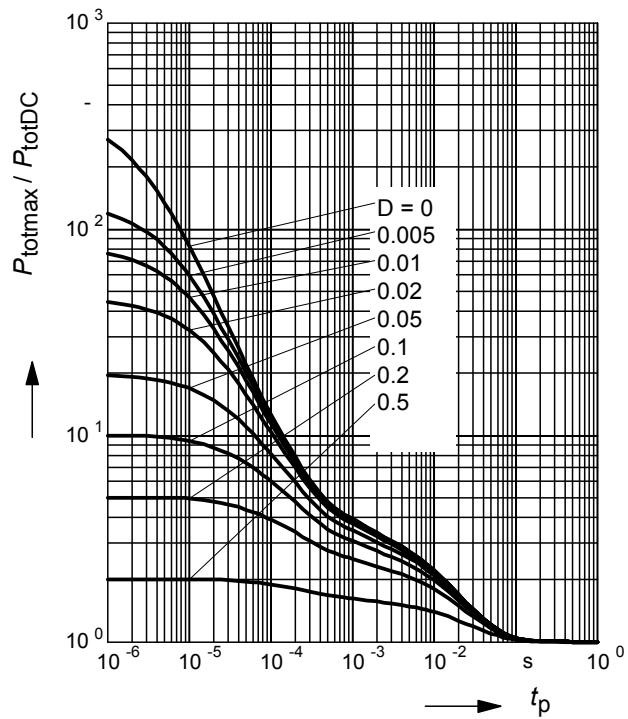

Permissible Puls Load $R_{\text{thJS}} = f(t_p)$

BCR135T


Permissible Pulse Load

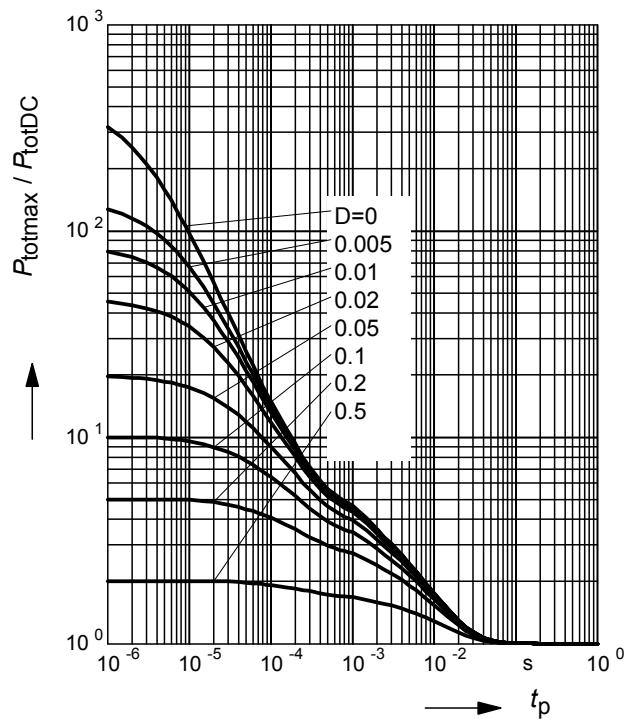
$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$$

BCR135S


Permissible Pulse Load

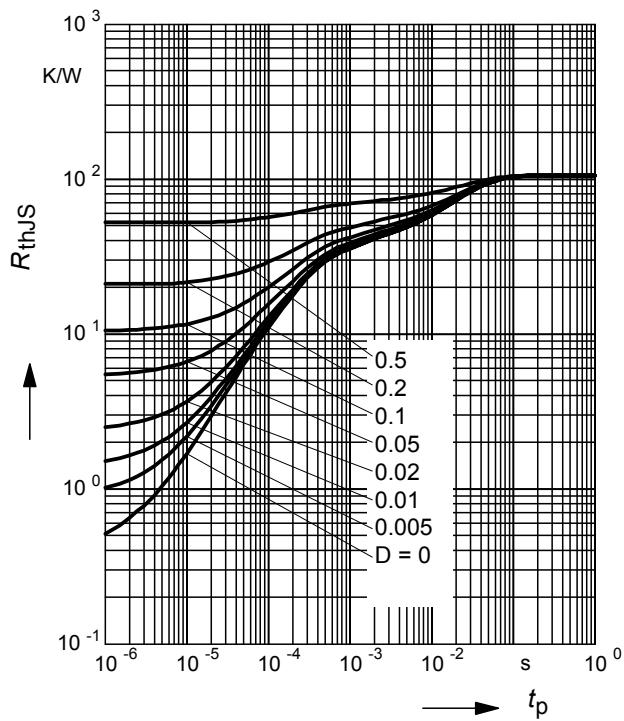
$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$$

BCR135T



Permissible Puls Load $R_{\text{thJS}} = f(t_p)$

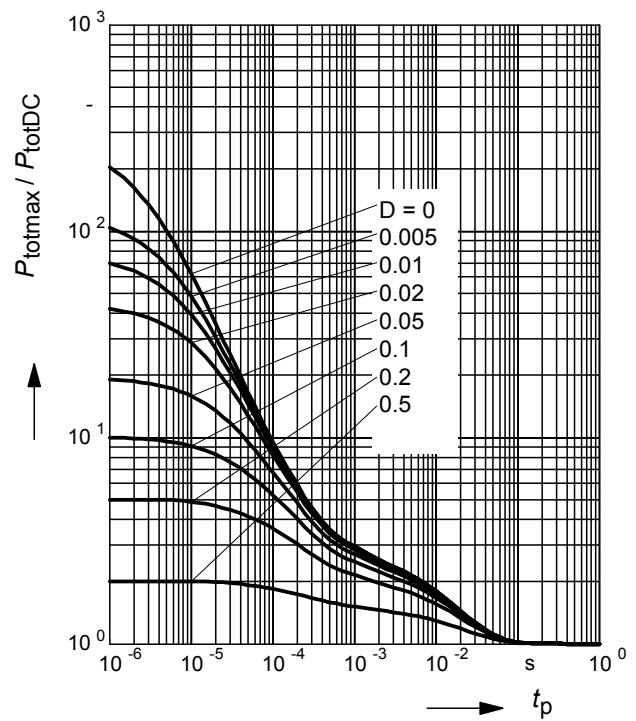
BCR135W



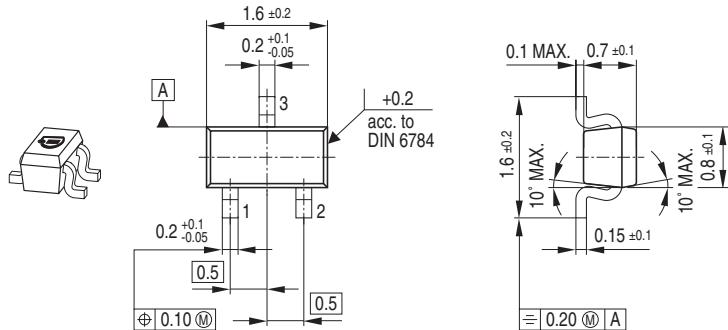
Permissible Pulse Load

$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$

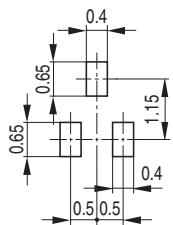
BCR135W



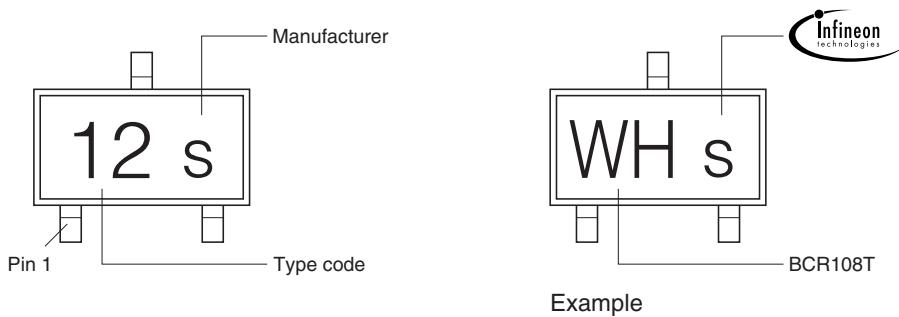
Package Outline



Foot Print



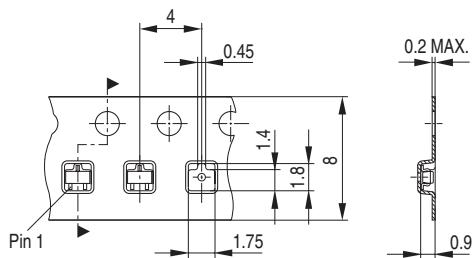
Marking Layout



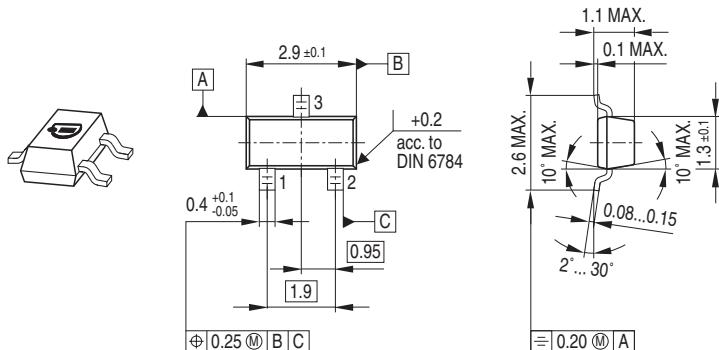
Packing

Code E6327: Reel ø180 mm = 3.000 Pieces/Reel

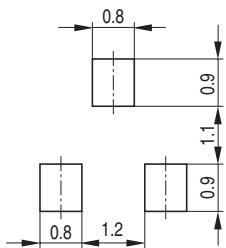
Code E6433: Reel ø330 mm = 10.000 Pieces/Reel



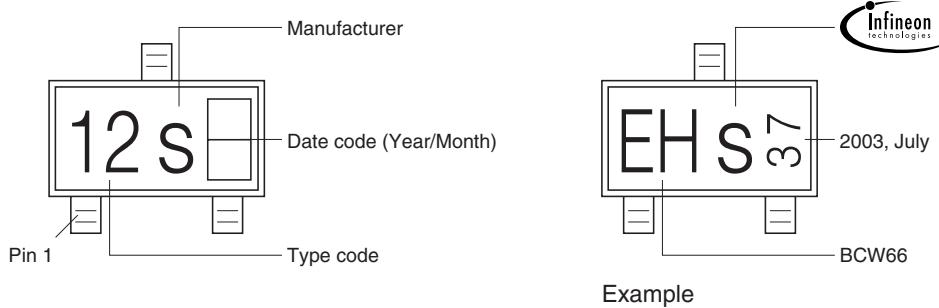
Package Outline



Foot Print



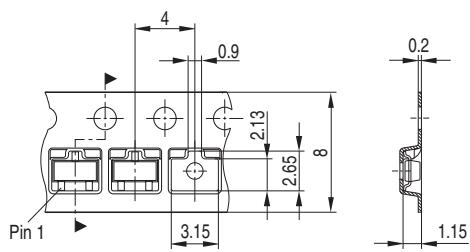
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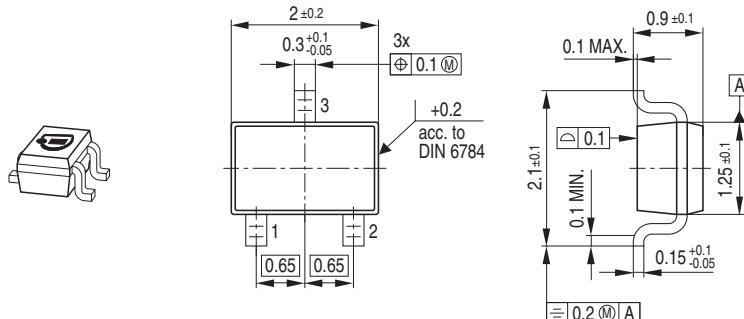
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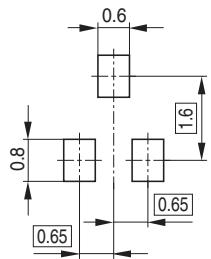
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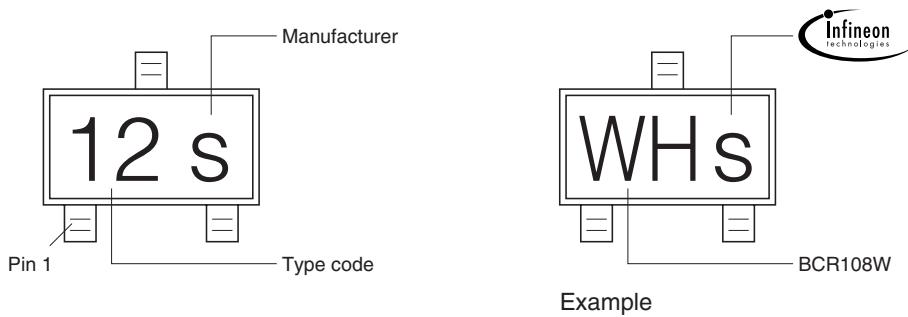
Package Outline



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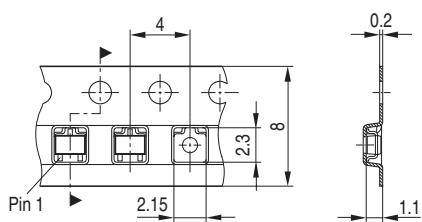


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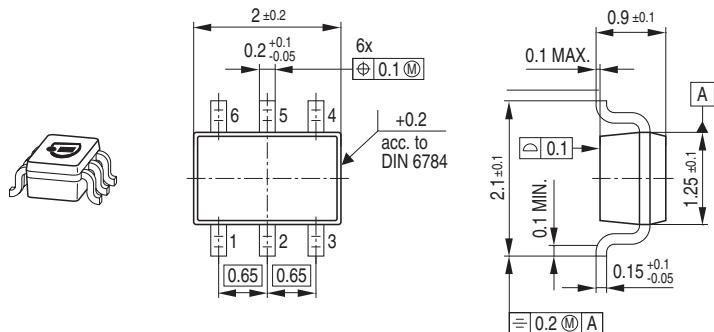


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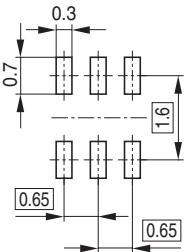
Code E6327: Reel ø180 mm = 3.000 Pieces/Reel
 Code E6433: Reel ø300 mm = 10.000 Pieces/Reel



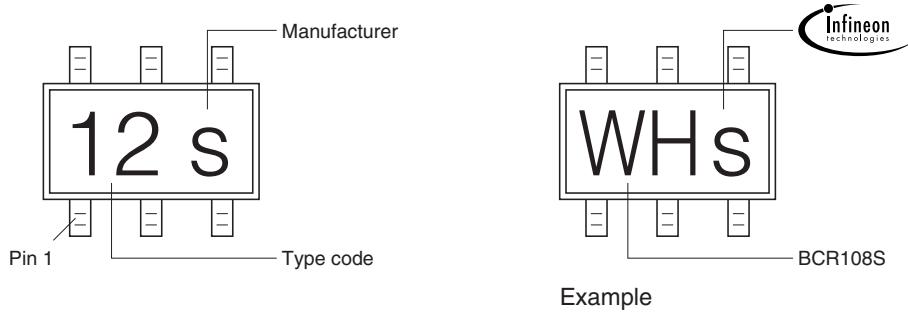
Package Outline



Foot Print



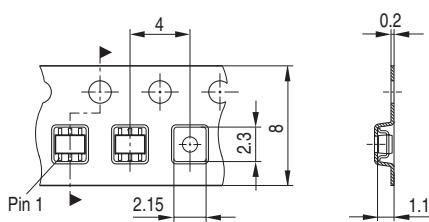
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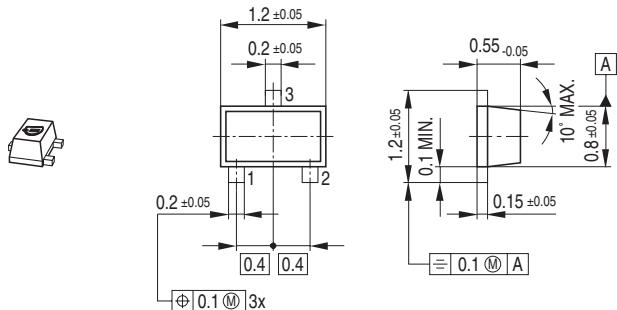
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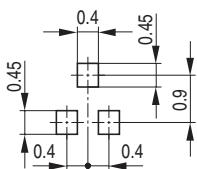
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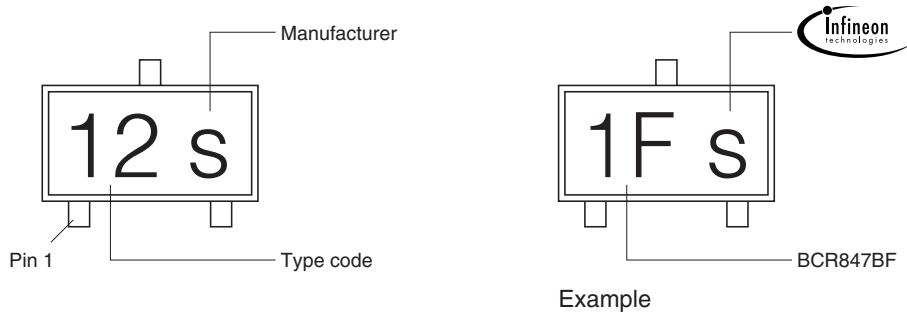
Package Outline



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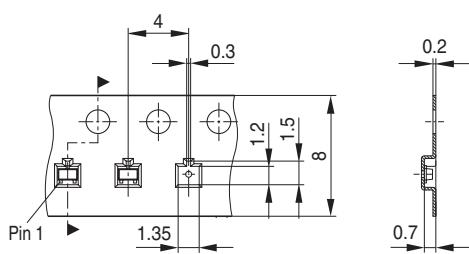


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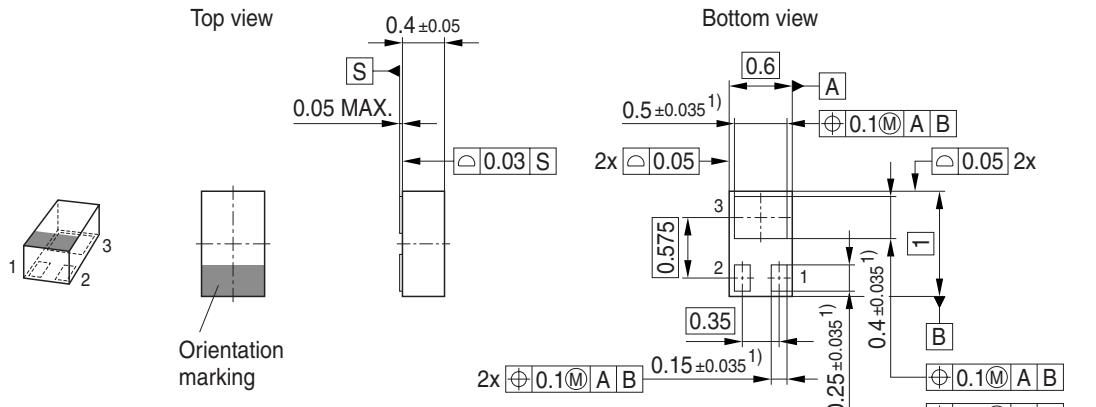


Packing

Code E6327: Reel ø180 mm = 3.000 Pieces/Reel
 Code E6433: Reel ø330 mm = 10.000 Pieces/Reel

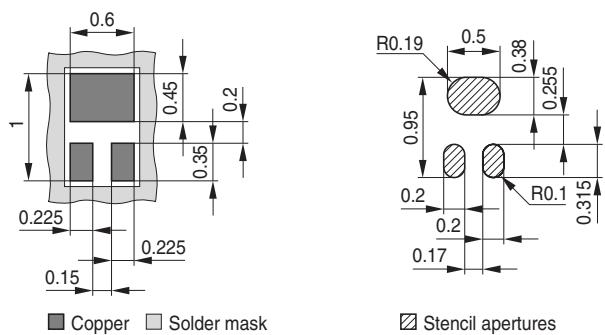


Package Outline

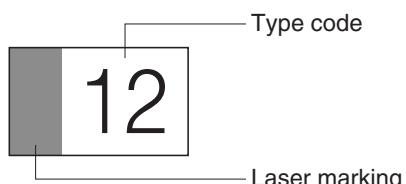


1) Dimension applies to plated terminals

Foot Print

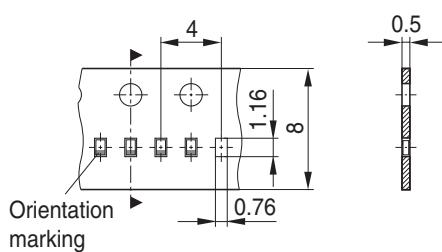


Marking Layout



Packing

Code E6327: Reel ø180 mm = 15.000 Pieces/Reel



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